503380090 07/06/2015

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date	
TAO LIN	03/08/2010	

RECEIVING PARTY DATA

Name:	Hangzhou H3C Technologies Co., Ltd.		
Street Address:	466 Changhe Road, Binjiang District		
Internal Address:			
City:	Hangzhou, Zhejiang		
State/Country:	CHINA		
Postal Code:	310052		

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14737295

CORRESPONDENCE DATA

Fax Number: (970)778-4063

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Correspondent Name: **HEWLETT-PACKARD COMPANY** Address Line 1: 3404 E. HARMONY ROAD MS 35

Address Line 2: INTELLECTUAL PROPERTY ADMINISTRATION

Address Line 4: FORT COLLINS, COLORADO 80528

TTORNEY DOCKET NUMBER: 84278524	
NAME OF SUBMITTER:	TIMOTHY B. KANG
SIGNATURE:	/Timothy B. Kang/
DATE SIGNED:	07/06/2015

Total Attachments: 1

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PATENT REEL: 036002 FRAME: 0543 503380090

PATENT ASSIGNMENT

WHEREAS, I, Tao Lin, a citizen of the PRC, residing at 602-1-23, Longyue 2, Huilongguan, Changping District, Beijing City, the PRC 102208, have made an invention which invention is claimed and described in an application for Letters Patent of the United States of America entitled "Method and Apparatus for Dual Stack Access," filed or to soon be filed in the U.S. Patent and Trademark Office, and executed on even date in anticipation of said filing; and

WHEREAS, HANGZHOU H3C TECHNOLOGIES CO., LTD. of Huawei Hangzhou Manufacturing Base, 310 Liuhe Road, Zhijiang Hi-Tech Park, Hangzhou Hi-Tech Industry Development Zone, Hangzhou City, Zhejiang Province, the PRC 310053 (hereinafter referred to as H3C) is desirous of acquiring the entire right, title and interest in and to the invention and in and to any Letters Patent that may be granted therefore;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I the undersigned party by these presents do sell, assign and transfer unto H3C, its successors and assigns the full, exclusive and worldwide right to the said invention including the United States of America, and the entire right, title and interest in, to and under any Letters Patent which may be granted on said invention, or any parts thereof, or on any continuation, division or reissue thereof in the United States of America, in the territorial possessions of the United States of America and in any country foreign to the United States of America, the same to be held and enjoyed by H3C its successors and assigns as fully and entirely as the same would have been held by me, had this assignment not been made.

And I, do hereby agree for myself and for my heirs, executors and administrators to execute any lawful document and to testify as to any material fact or thing which H3C, its successors and assigns may deem necessary in order to secure unto itself, its successors and assigns the full right, title and interest in and to and the full enjoyment of said invention or any part thereof and any Letters Patent, the same to be done without any further consideration.

And, I hereby authorize my attorney to insert here in parentheses (Application No.

	, i nereby ar	, filed		to msen	arenmeses : filing date	
number of a	said applicati	on when kn	own.			
Ta0	Lin					

Mar 8, 2010

PATENT REEL: 036002 FRAME: 0544

RECORDED: 07/06/2015